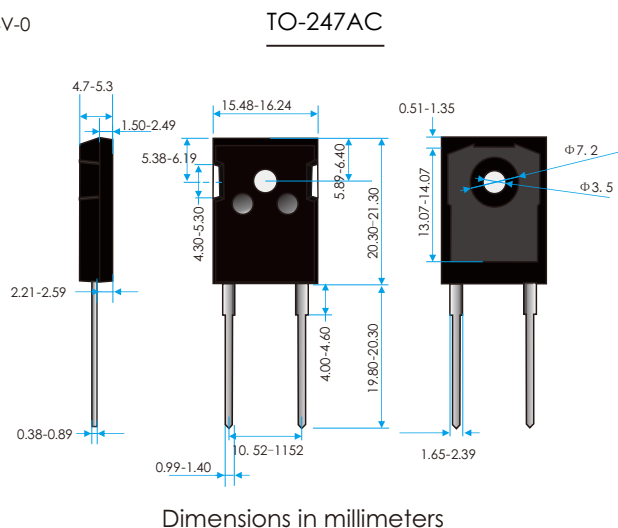


FEATURES

- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- Fred Chip Planar Construction
- Low forward voltage drop
- Ultrafast Recovery Time
- Soft Recovery Characteristics
- For use in free wheeling, snubber, clamp, inversion welder, PFC, Plating Power Supply
- High temperature soldering guaranteed:260°C/10 seconds, 0.25"(6.35mm)from case
- Component in accordance to RoHS 2011/65/EU

MECHANICAL DATA

- Case: TO-247AC molded plastic body
- Terminals: Lead solderable per MIL-STD-750,method 2026
- Polarity: As marked
- Mounting Position: Any



ABSOLUT MAXIMUM RATINGS (T_C=25°C unless otherwise specified)

Symbol	Parameter/Test Conditions		Values	Unit
V _R	Maximum DC blocking voltage		600	V
V _{RRM}	Maximum repetitive peak reverse voltage		600	V
I _{F(AV)}	Average forward current	T _C =110°C	30	A
I _{F(RMS)}	RMS forward current	T _C =110°C	42	A
I _{FSM}	NON Repetitive Surge Forward Current	T _J =45°C, t=10ms, 50HZ, Sine	300	A
P _D	Power Dissipation		156	W
T _J	Junction temperature		-55 to+150	°C
T _{STG}	Storage temperature range		-55 to+150	°C
Torque	Module to Sink		1.1	Nm
R _{θJC}	Junction to Case Thermal Resistance		0.44	°C/W

RATINGS AND CHARACTERISTIC OF MUR3060P

ELECTRICAL CHARACTERISTICS (T_c=25°C unless otherwise specified)

Symbol	Parameter/Test Conditions		Min.	Typ.	Max.	Unit
I _{RM}	Maximum Reverse Leakage Current	V _R =600V	-	-	5	μA
I _{RM}	Maximum Reverse Leakage Current	V _R =600V, T _J =125°C	-	-	250	μA
V _F	Forward Voltage	I _F =30A	-	1.5	1.8	V
V _F	Forward Voltage	I _F =30A, T _J =125°C	-	1.3	-	V
t _{rr}	Reverse Recovery Time (I _F =1A, dI _F /dt=-200A/μs, V _R =30V)		-	32	-	ns
t _{rr}	Reverse Recovery Time	I _F =30A, V _R =300V dI _F /dt=-200A/μs	-	50	-	ns
I _{RRM}	Maximum Reverse Recovery Current		-	4.2	-	A
t _{rr}	Reverse Recovery Time	I _F =30A, V _R =300V dI _F /dt=-200A/μs, T _J =125°C	-	130	-	ns
I _{RRM}	Maximum Reverse Recovery Current		-	9	-	A

FIG.1-Forward Voltage Drop vs Forward Current

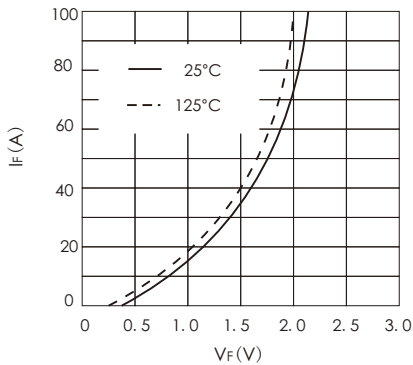
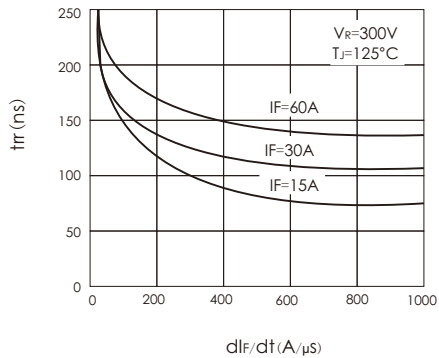


FIG.2-Reverse Recovery Time vs dI_F/dt



RATINGS AND CHARACTERISTIC OF MUR3060P

FIG.3-Reverse Recovery Current vs di_f/dt

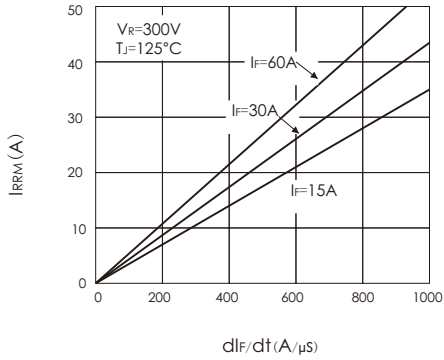


FIG.4-Reverse Recovery Charge vs di_f/dt

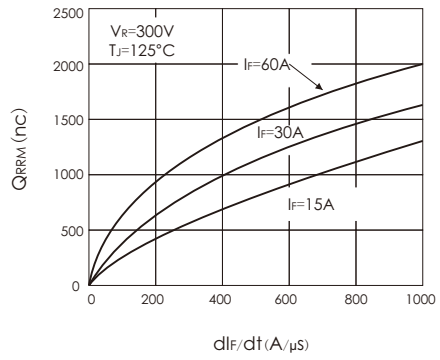


FIG.5-Dynamic Parameters vs Junction Temperature

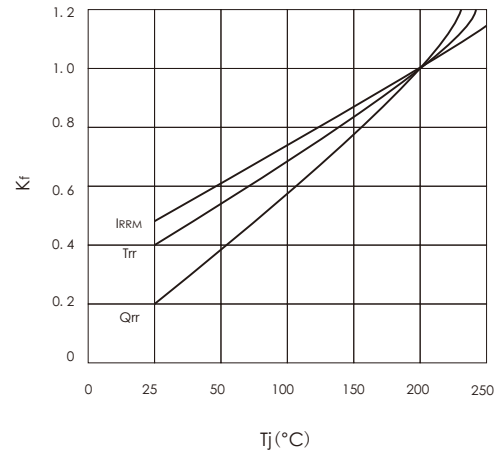


FIG.6-Transient Thermal Impedance

